

NMB Semiconductor

AAA1M204 Fast Page Mode CMOS 256K × 4 Dynamic RAM

PRELIMINARY

FEATURES

- 262,144 × 4 bit Organization
- Single 5V ±10% Power Supply
- Performance Ranges:

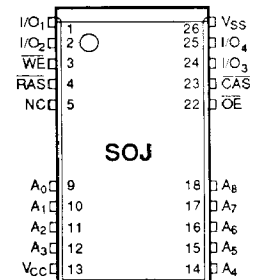
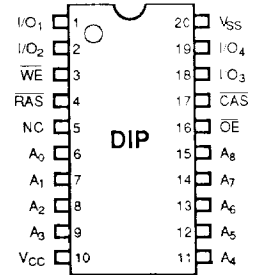
Parameter	-06	-07	-08	-10
Max. $\overline{\text{RAS}}$ Access Time	60ns	70ns	80ns	100ns
Max. $\overline{\text{CAS}}$ Access Time	15ns	20ns	20ns	25ns
Max. Column Address Access Time	30ns	35ns	40ns	50ns
Min. Read/Write Cycle Time	110ns	130ns	150ns	190ns

- Fast page mode operation

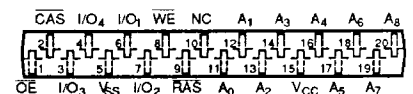
- Low Power Operation
 - Standby current (CMOS) 2mA
 - Operating current 80mA
- 512 Refresh cycles distributed across 8ms
- All input and output clocks are fully TTL and CMOS compatible
- Refresh modes: $\overline{\text{RAS}}$ only, $\overline{\text{CAS}}$ before $\overline{\text{RAS}}$ and hidden refresh
- High reliability plastic 20 pin 300 mil wide DIP, plastic 26pin SOJ, and plastic 20pin ZIP.

PIN CONFIGURATIONS

(TOP VIEWS)



ZIP



DESCRIPTION

The AAA1M204 is a high performance CMOS Dynamic Random Access Memory organized as 262,144 words by 4 bits. The AAA1M204 is fabricated with advanced CMOS technology and designed with innovative design techniques resulting in high speed, extremely low power and wide operating margins at both component and system levels.

The AAA1M204 features a high speed page mode operation in which high speed read, write and read-write is performed on any of the 1,024 bits defined by the column address. The asynchronous column address eases the system level timing constraints associated with a multiplexed address scheme with an extremely short row address capture time. The output is tri-stated by $\overline{\text{CAS}}$ which, in essence, acts as an output enable independent of $\overline{\text{RAS}}$ with very fast $\overline{\text{CAS}}$ to output access time.

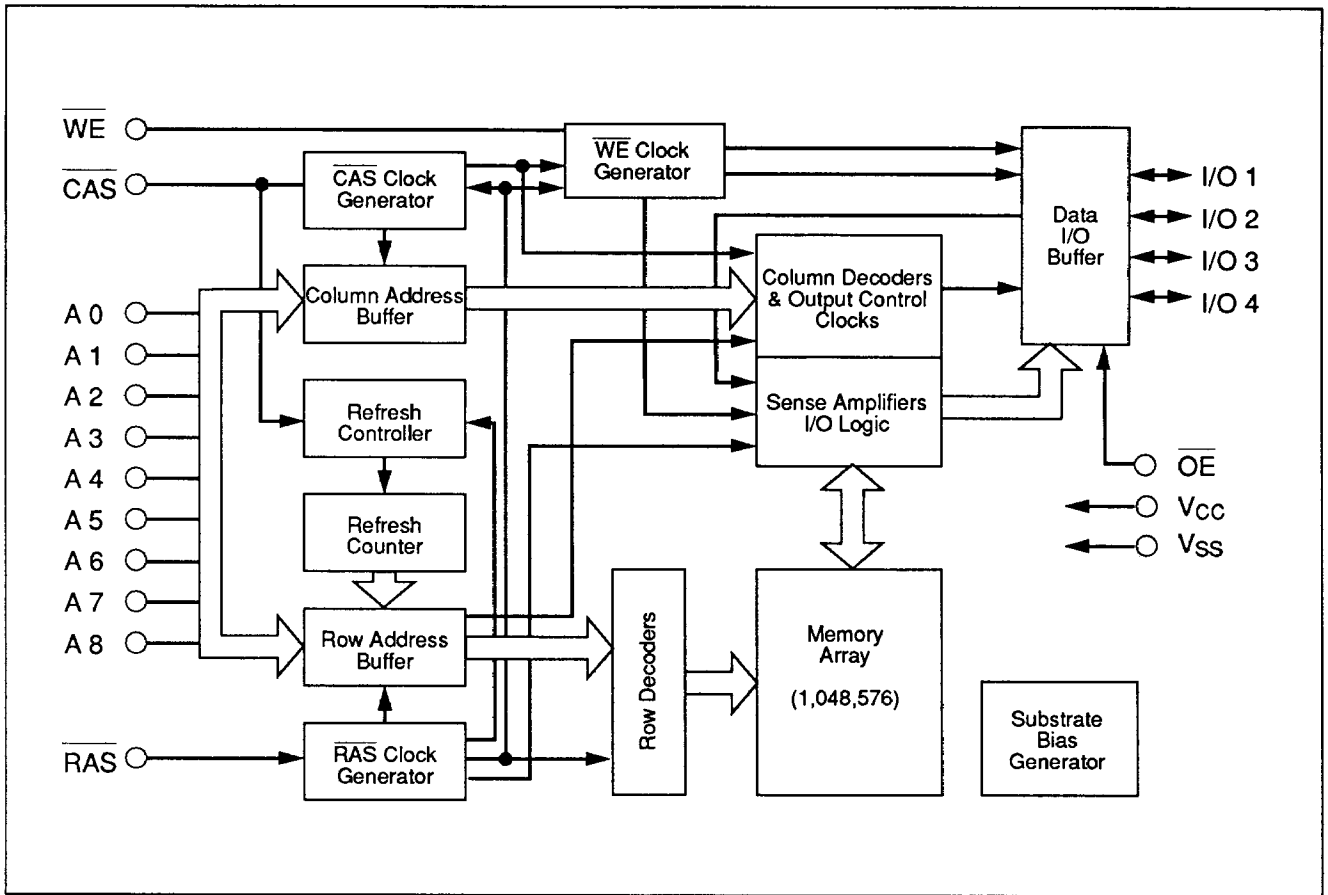
Refresh is accomplished by performing $\overline{\text{RAS}}$ only refresh cycles, hidden refresh cycles, $\overline{\text{CAS}}$ before $\overline{\text{RAS}}$ refresh cycles, or normal read or write cycles on the 512 address combinations of A0 to A8 during an 8ms period.

Multiplexed address inputs permit AAA1M204 to be packaged in a standard 20-pin plastic DIP, 26-pin plastic SOJ and 20-pin plastic ZIP. The package sizes provide high system densities and are compatible with widely available automated testing and insertion equipment. System level features include single power supply of 5V ±10% tolerance and direct interface with high performance TTL logic families.

PIN NAMES

A0-A8	Address Inputs
$\overline{\text{RAS}}$	Row Address Strobe
$\overline{\text{CAS}}$	Column Address Strobe
$\overline{\text{OE}}$	Output Enable
I/O1-I/O4	Data-in / Data-out
$\overline{\text{WE}}$	Write Enable
Vcc	+5V Supply
Vss	Ground
NC	No Connection

FUNCTIONAL BLOCK DIAGRAM



ABSOLUTE MAXIMUM RATINGS

RATING	SYMBOL	VALUE	UNIT
Voltage on Any Pin Relative to V _{SS}	V _{in} , V _{out}	-1 to 7	V
Voltage on V _{CC} Relative to V _{SS}	V _{CC}	-1 to 7	V
Storage Temperature (Plastic)	T _{stg}	-55 to 125	°C
Power Dissipation	P _d	600	mW
Ambient Operating Temperature	T _a	0 to + 70	°C

* Permanent device damage can occur if absolute maximum ratings are exceeded. Functional operation should be restricted to the conditions as detailed in the operational sections of this data sheet. Exposure to absolute maximum rating conditions for extended periods can affect device reliability.

DC OPERATING CONDITIONS

SYMBOL	PARAMETER	MIN.	TYP.	MAX.	UNIT
V _{CC}	Supply Voltage	4.5	5.0	5.5	V
V _{SS}	Supply Voltage		0		V
V _{IH}	Input High Voltage, All Inputs	2.4		6.5	V
V _{IL}	Input Low Voltage, All Inputs	-1.0		0.8	V

Note: All voltage values in this data sheet are with respect to V_{SS}.

DC ELECTRICAL CHARACTERISTICS (0°C ≤ Ta ≤ 70°C, V_{CC} = 5.0V ±10%)

SYMBOL	PARAMETER	SPEED	MIN.	MAX.	UNIT	TEST CONDITIONS	NOTE
I _{CC1}	Average V _{CC} Power Supply Current (Operating)	-06		95	mA	t _{RC} = t _{RC} (min.) RAS, CAS, Address Cycling	1, 2
		-07		95	mA		
		-08		95	mA		
		-10		80	mA		
I _{CC2}	V _{CC} Supply Current (TTL standby)			3	mA	RAS and CAS at V _{IH} . All Other Inputs ≥ V _{SS}	
I _{CC3}	V _{CC} Supply Current (RAS only refresh)	-06		95	mA	t _{RC} = t _{RC} (min.) RAS Cycling, CAS = V _{IH}	1
		-07		95	mA		
		-08		95	mA		
		-10		80	mA		
I _{CC4}	V _{CC} Supply Current (Fast page mode)	-06		75	mA	t _{PC} = t _{PC} (min.) RAS = V _{IL} CAS, Address Cycling	1, 2
		-07		75	mA		
		-08		75	mA		
		-10		60	mA		
I _{CC5}	V _{CC} Supply Current (CAS before RAS refresh)	-06		95	mA	t _{RC} = t _{RC} (min.) RAS, CAS Cycling	1
		-07		95	mA		
		-08		95	mA		
		-10		80	mA		
I _{CC6}	V _{CC} Supply Current (CMOS standby)			2	mA	RAS ≥ V _{CC} -0.2V and CAS at V _{IH} All Other Inputs ≥ V _{SS}	
I _{I(L)}	Input Leakage Current (Any input pin)		-10	10	μA	0V ≥ V _{IN} ≥ V _{CC} , Others = 0V	
I _{O(L)}	Output Leakage Current (For high impedance state)		-10	10	μA	RAS at V _{IH} , CAS at V _{IH} 0V ≤ V _{OUT} ≤ V _{CC}	
V _{OH}	Output High Voltage		2.4		V	I _{OH} = -5.0 mA	
V _{OL}	Output Low Voltage			0.4	V	I _{OL} = 4.2 mA	

- Notes: 1. I_{CC1}, I_{CC3}, I_{CC4} and I_{CC5} depend on cycle rate.
2. I_{CC1} and I_{CC4} depend on output loading. Specified values are obtained with the output open.

CAPACITANCE (0°C ≤ Ta ≤ 70°C, V_{CC} = 5.0V ±10%, f = 1MHz)

SYMBOL	PARAMETER	MIN.	MAX.	UNIT
C _{IN}	Address, D _{IN}	—	5	pF
C _{IN}	RAS, CAS, WE	—	7	pF
C _{OUT}	Output Capacitance	—	7	pF

AAA1M204
CMOS 256K × 4 Dynamic RAM

A.C. OPERATING CONDITIONS (0°C ≤ Ta ≤ 70°C, V_{CC} = 5 V ± 10%, V_{SS} = 0 V) (NOTES 3, 4, 5)

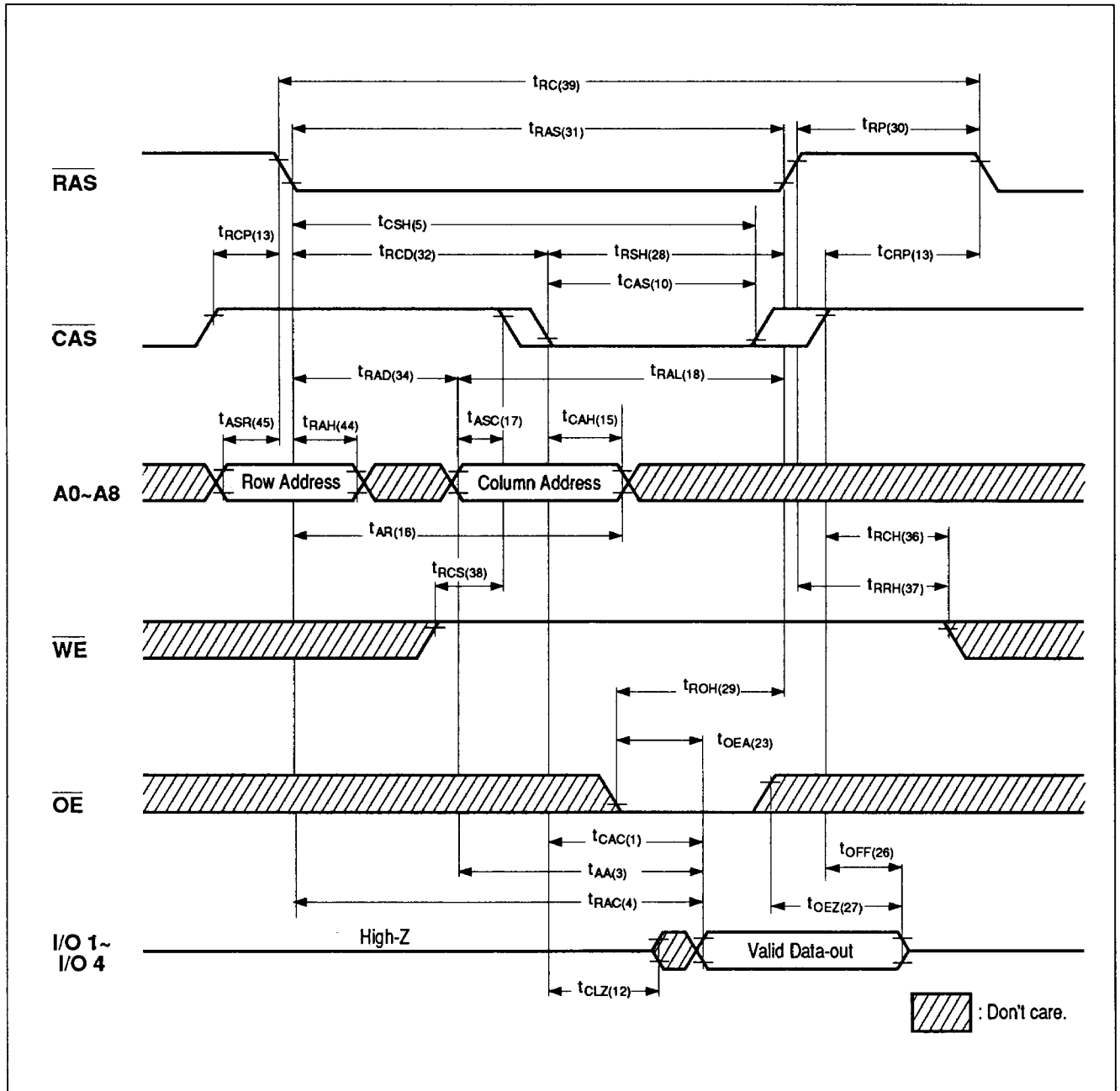
NO.	SYMBOL		PARAMETER	1M204-06		1M204-07		1M204-08		1M204-10		UNIT	NOTE
	JEDEC	STD.		MIN.	MAX.	MIN.	MAX.	MIN.	MAX.	MIN.	MAX.		
1	t _{CL1QV}	t _{CAC}	Access Time from $\overline{\text{CAS}}$	—	15	—	20	—	20	—	25	ns	6
2	t _{CH2QV}	t _{CPA}	Access Time from $\overline{\text{CAS}}$ Precharge	—	40	—	45	—	50	—	55	ns	13
3	t _{AVQV}	t _{AA}	Access Time from Column Address	—	30	—	35	—	40	—	50	ns	7
4	t _{RL1QV}	t _{RAC}	Access Time from $\overline{\text{RAS}}$	—	60	—	70	—	80	—	100	ns	6
5	t _{RL1CH1}	t _{CSH}	$\overline{\text{CAS}}$ Hold Time	60	—	70	—	80	—	100	—	ns	
6	t _{RL1CH1}	t _{CHR}	$\overline{\text{CAS}}$ Hold Time ($\overline{\text{CAS}}$ before $\overline{\text{RAS}}$ Refresh)	30	—	30	—	30	—	30	—	ns	
7	t _{CH2CL2}	t _{CPN}	$\overline{\text{CAS}}$ Precharge Time ($\overline{\text{CAS}}$ before $\overline{\text{RAS}}$ Refresh)	10	—	10	—	10	—	15	—	ns	
8	t _{CH2CL2}	t _{CPT}	$\overline{\text{CAS}}$ Precharge Time ($\overline{\text{CAS}}$ before $\overline{\text{RAS}}$ Counter Test)	30	—	40	—	40	—	50	—	ns	
9	t _{CH2CL2}	t _{CP}	$\overline{\text{CAS}}$ Precharge Time (Fast Page Mode)	10	—	10	—	10	—	10	—	ns	
10	t _{CL1CH1}	t _{CAS}	$\overline{\text{CAS}}$ Pulse Width	15	10K	20	10K	20	10K	25	10K	ns	
11	t _{CL1RL2}	t _{CSR}	$\overline{\text{CAS}}$ Setup Time ($\overline{\text{CAS}}$ before $\overline{\text{RAS}}$ Refresh)	10	—	10	—	10	—	10	—	ns	
12	t _{CL1QV}	t _{CLZ}	$\overline{\text{CAS}}$ to Output in Low-Z	0	—	0	—	0	—	0	—	ns	8
13	t _{CH2RL2}	t _{CRP}	$\overline{\text{CAS}}$ to $\overline{\text{RAS}}$ Precharge Time	5	—	5	—	5	—	5	—	ns	
14	t _{CL1WL2}	t _{CWD}	$\overline{\text{CAS}}$ to $\overline{\text{WE}}$ Delay Time	45	—	50	—	50	—	65	—	ns	11
15	t _{CL1AX}	t _{CAH}	Column Address Hold Time	10	—	15	—	15	—	20	—	ns	
16	t _{RL1AX}	t _{AR}	Column Address Hold Time Referenced to $\overline{\text{RAS}}$	50	—	55	—	60	—	75	—	ns	
17	t _{AVCL2}	t _{ASC}	Column Address Setup Time	0	—	0	—	0	—	0	—	ns	
18	t _{AVRH1}	t _{RAL}	Column Address to $\overline{\text{RAS}}$ Lead Time	30	—	35	—	40	—	50	—	ns	
19	t _{AWWL2}	t _{AWD}	Column Address to $\overline{\text{WE}}$ Delay Time	60	—	65	—	70	—	85	—	ns	11
20	t _{CL1DX} t _{WL1DX}	t _{DH}	Data Hold Time	10	—	15	—	15	—	20	—	ns	13
21	t _{RL1DX}	t _{DHR}	Data Hold Time Referenced to $\overline{\text{RAS}}$	50	—	55	—	60	—	75	—	ns	
22	t _{DVCL2} t _{DVWL2}	t _{DS}	Data Setup Time	0	—	0	—	0	—	0	—	ns	13
23	t _{OL1QV}	t _{OEA}	$\overline{\text{OE}}$ Access Time	—	15	—	20	—	20	—	25	ns	
24	t _{WL1OL2}	t _{OEH}	$\overline{\text{OE}}$ Command Hold Time	15	—	20	—	20	—	25	—	ns	
25	t _{OH2QV}	t _{OED}	$\overline{\text{OE}}$ to Data Delay Time	15	—	20	—	20	—	25	—	ns	
26	t _{CH2QX}	t _{OFF}	Output Buffer Turn-off Delay Time	0	15	0	20	0	20	0	30	ns	10
27	t _{OH2QX}	t _{OEZ}	Output Buffer Turn-off Delay Time Referenced to $\overline{\text{OE}}$	0	15	0	20	0	20	0	25	ns	
28	t _{CL1RH1}	t _{RSH}	$\overline{\text{RAS}}$ Hold Time	15	—	20	—	20	—	25	—	ns	
29	t _{OL1RH1}	t _{ROH}	$\overline{\text{RAS}}$ Hold Time Referenced to $\overline{\text{OE}}$	10	—	10	—	10	—	20	—	ns	
30	t _{RH2RL2}	t _{RP}	$\overline{\text{RAS}}$ Precharge Time	40	—	50	—	60	—	70	—	ns	
31	t _{RL1RH1}	t _{RAS}	$\overline{\text{RAS}}$ Pulse Width	60	100K	70	100K	80	100K	100	100K	ns	
32	t _{RL1CL1}	t _{RCD}	$\overline{\text{RAS}}$ to $\overline{\text{CAS}}$ Delay Time	15	45	20	50	20	60	25	75	ns	6
33	t _{RH2CL2}	t _{RPC}	$\overline{\text{RAS}}$ to $\overline{\text{CAS}}$ Precharge Time	0	—	0	—	0	—	0	—	ns	
34	t _{RL1AV}	t _{RAD}	$\overline{\text{RAS}}$ to Column Address Delay Time	15	30	15	35	15	40	20	50	ns	7
35	t _{RL1WL2}	t _{RWD}	$\overline{\text{RAS}}$ to $\overline{\text{WE}}$ Delay Time	90	—	100	—	110	—	135	—	ns	11
36	t _{CH2WL2}	t _{RCH}	Read Command Hold Time	0	—	0	—	0	—	0	—	ns	9
37	t _{RH2WL2}	t _{RRH}	Read Command Hold Time Referenced to $\overline{\text{RAS}}$	0	—	0	—	0	—	0	—	ns	9
38	t _{WH2CL2}	t _{RCS}	Read Command Setup Time	0	—	0	—	0	—	0	—	ns	

NO.	SYMBOL		PARAMETER	1M204-06		1M204-07		1M204-08		1M204-10		UNIT	NOTE
	JEDEC	STD.		MIN.	MAX.	MIN.	MAX.	MIN.	MAX.	MIN.	MAX.		
39	t_{RL2RL2}	t_{RC}	Random Read or Write Cycle Time	110	—	130	—	150	—	190	—	ns	
40	t_{CL2CL2}	t_{PC}	Read or Write Cycle Time (Fast Page Mode)	40	—	45	—	50	—	55	—	ns	13,14
41	t_{RL2RL2}	t_{RMW}	Read-Modify-Write Cycle Time	165	—	185	—	205	—	245	—	ns	
42	t_{CL2CL2}	t_{PRMW}	Read-Modify-Write Cycle Time (Fast Page Mode)	95	—	100	—	105	—	125	—	ns	13,14
43	t_{REF}	t_{REF}	Refresh Period	—	8	—	8	—	8	—	8	ms	
44	t_{RL1AX}	t_{RAH}	Row Address Hold Time	10	—	12	—	12	—	15	—	ns	
45	t_{AVRL2}	t_{ASR}	Row Address Setup Time	0	—	0	—	0	—	0	—	ns	
46	t_T	t_T	Transition Time (Rise and Fall)	3	50	3	50	3	50	3	50	ns	4, 5
47	t_{CL1WH1}	t_{WCH}	Write Command Hold Time	10	—	15	—	15	—	20	—	ns	
48	t_{RL1WH1}	t_{WCR}	Write Command Hold Time Referenced to RAS	50	—	55	—	60	—	75	—	ns	
49	t_{WL1WH1}	t_{WP}	Write Command Pulse Width	10	—	10	—	15	—	20	—	ns	
50	t_{WL1CL2}	t_{WCS}	Write Command Setup Time	0	—	0	—	0	—	0	—	ns	11
51	t_{WL1CH1}	t_{CWL}	Write Command to \overline{CAS} Lead Time	15	—	20	—	20	—	25	—	ns	
52	t_{WL1RH1}	t_{RWL}	Write Command to \overline{RAS} Lead Time	15	—	20	—	20	—	25	—	ns	

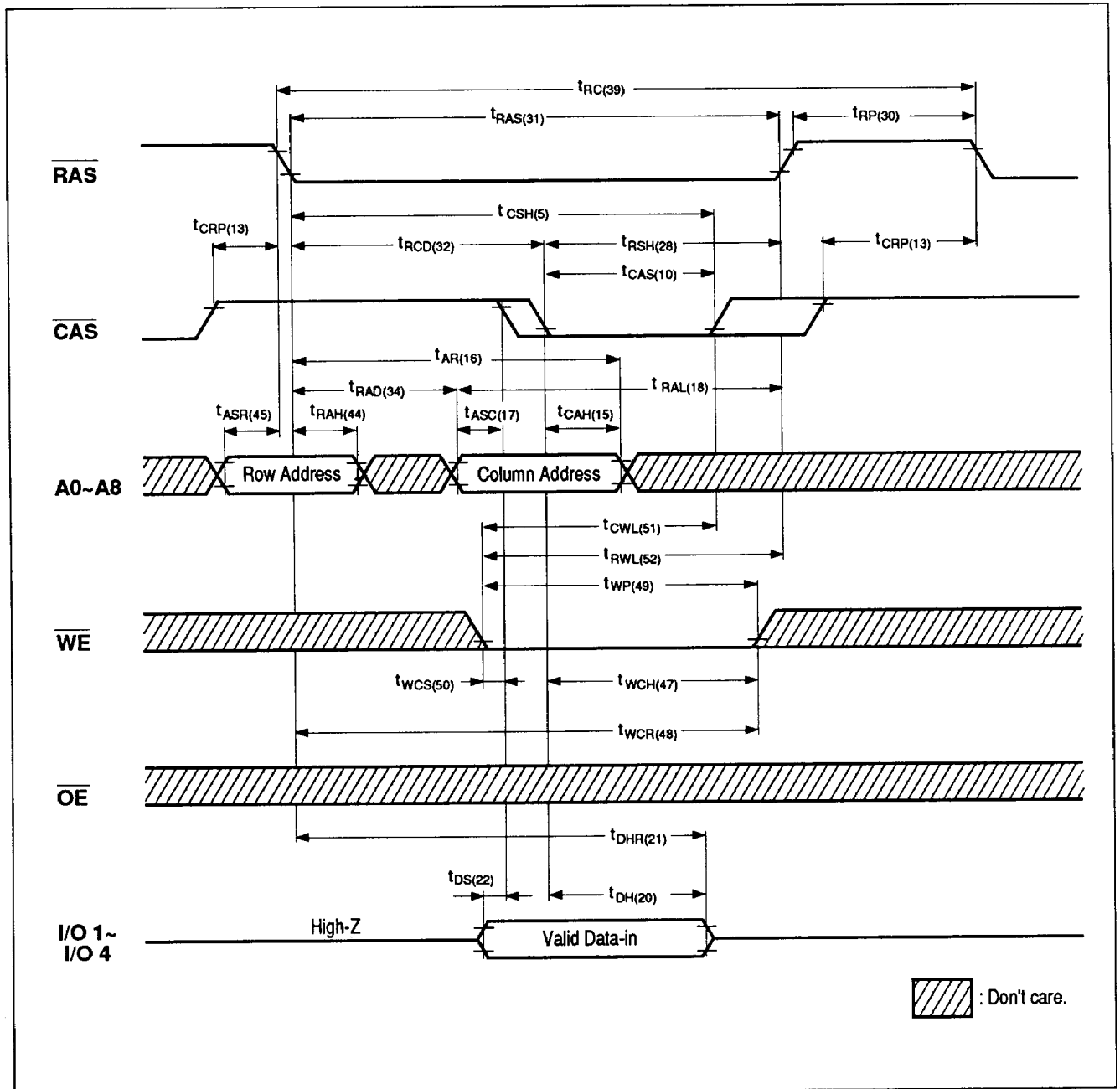
Notes:

3. Following power up, an initial pause of 200 μ s is required followed by any 8 \overline{RAS} cycles before proper device operation is achieved. In case of using internal refresh counter, a minimum of 8 \overline{CAS} before \overline{RAS} initialization cycles instead of 8 \overline{RAS} cycles are required. Eight initialization cycles are required after extended periods of bias without clocks (greater than 8ms).
4. AC measurements assume $t_T=5$ ns. All AC parameters are measured with $V_{IL}(\text{min.}) \geq V_{SS}$ and $V_{IH}(\text{max.}) \leq V_{CC}$ and with a load equivalent to two TTL loads and 100pF.
5. $V_{IH}(\text{min.})$ and $V_{IL}(\text{max.})$ are reference levels for measuring timing of input signals. Also, transition times are measured between V_{IH} and V_{IL} .
6. Operation within the $t_{RCD}(\text{max.})$ limit insures that $t_{RAC}(\text{max.})$ can be met. $t_{RCD}(\text{max.})$ is specified as a reference point only. If t_{RCD} is greater than the specified $t_{RCD}(\text{max.})$ limit, then access time is controlled by t_{CAC} .
7. Operation within the $t_{RAD}(\text{max.})$ limit insures that $t_{RAC}(\text{max.})$ can be met. $t_{RAD}(\text{max.})$ is specified as a reference point only. If t_{RAD} is greater than the specified $t_{RAD}(\text{max.})$ limit, then access time is controlled exclusively by t_{AA} .
8. Assumes three state test load (5pF and a 380 Ohm Thevenin equivalent).
9. Either t_{RCH} or t_{RRH} must be satisfied for a Read cycle.
10. $t_{OFF}(\text{max.})$ defines the time at which the output achieves an open circuit condition and is not referenced to output voltage levels.
11. t_{WCS} , t_{RWD} , t_{CWD} and t_{AWD} are not restrictive operating parameters. They are included in the data sheet as electrical characteristics only. If $t_{WCS} \geq t_{WCS}(\text{min.})$, the cycle is an Early Write cycle and the data-out pins will remain open circuit (high impedance) throughout the entire cycle. If $t_{RWD} \geq t_{RWD}(\text{min.})$, $t_{CWD} \geq t_{CWD}(\text{min.})$ and $t_{AWD} \geq t_{AWD}(\text{min.})$, the cycle is a Read-Modify-Write cycle and Data-out will contain data read from the selected cell. If neither of the above conditions is satisfied, the condition of Data-out (at access time) is indeterminate.
12. These parameters are referenced to \overline{CAS} leading edge in Early Write cycles and to \overline{WE} leading edge in Read-Modify-Write cycles.
13. Access time is determined by the longer of t_{AA} , t_{CAC} or t_{CPA} .
14. $t_{ASC} \geq t_{CP}$ to achieve $t_{PC}(\text{min.})$ and $t_{CPA}(\text{max.})$ values.

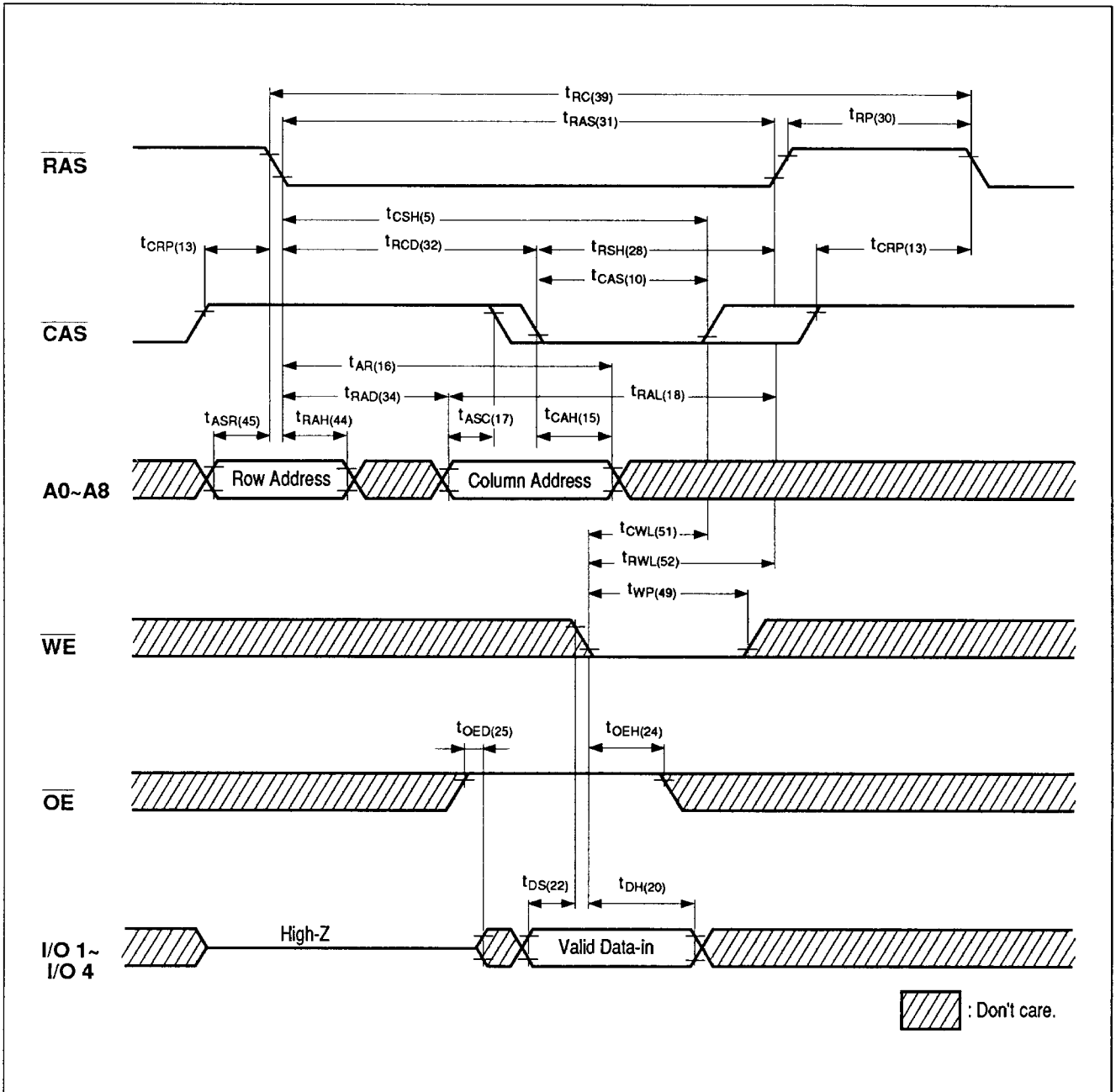
READ CYCLE



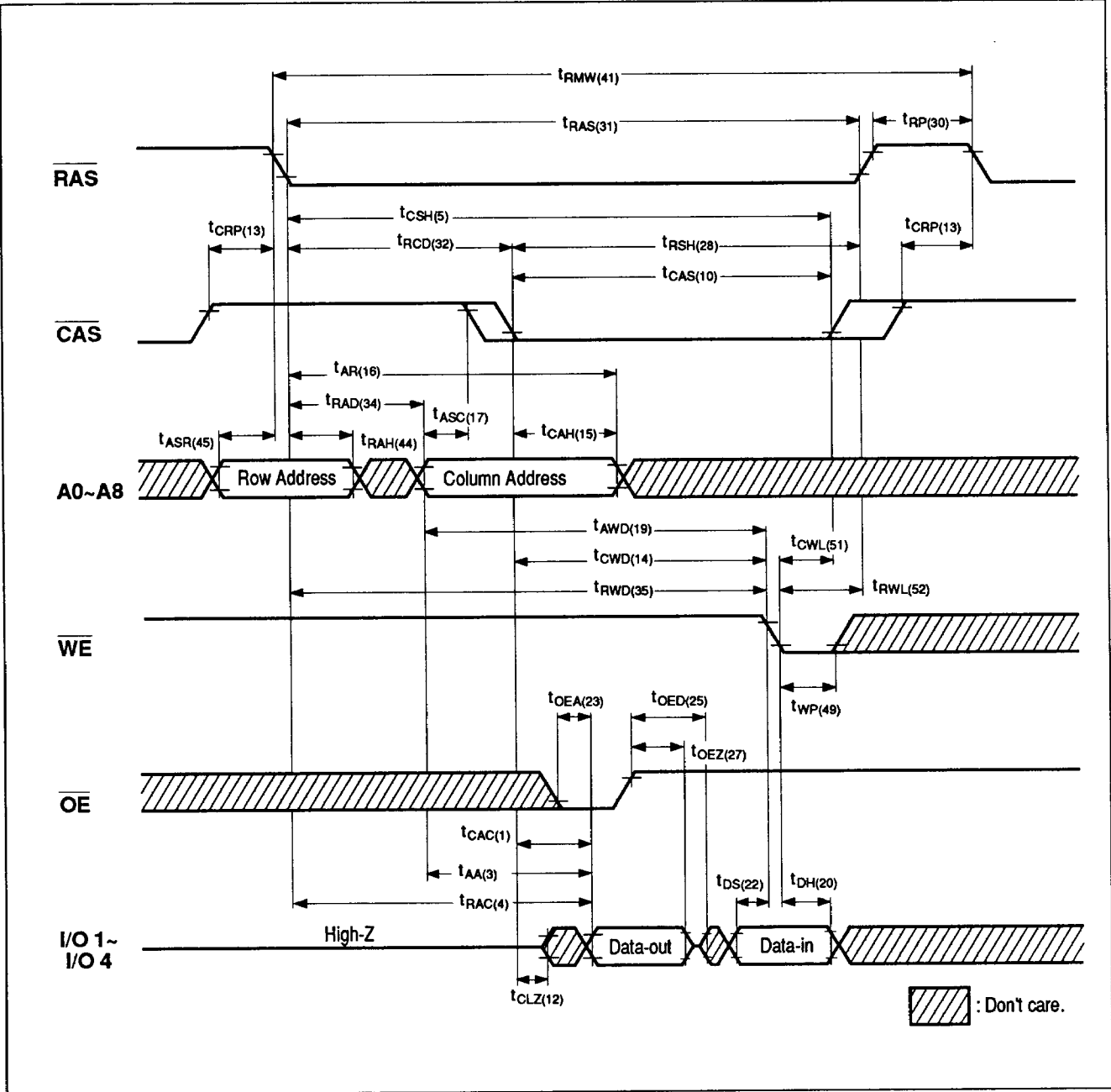
WRITE CYCLE (EARLY WRITE)



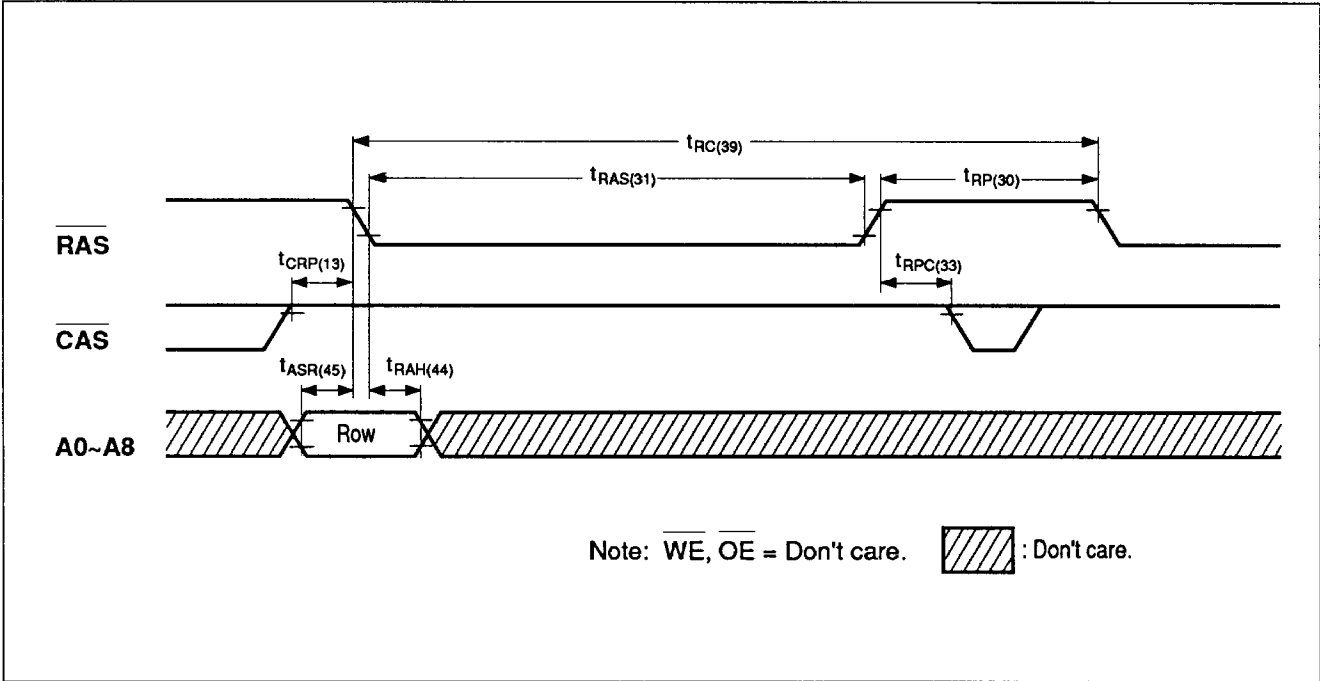
WRITE CYCLE (OE-CONTROLLED WRITE)



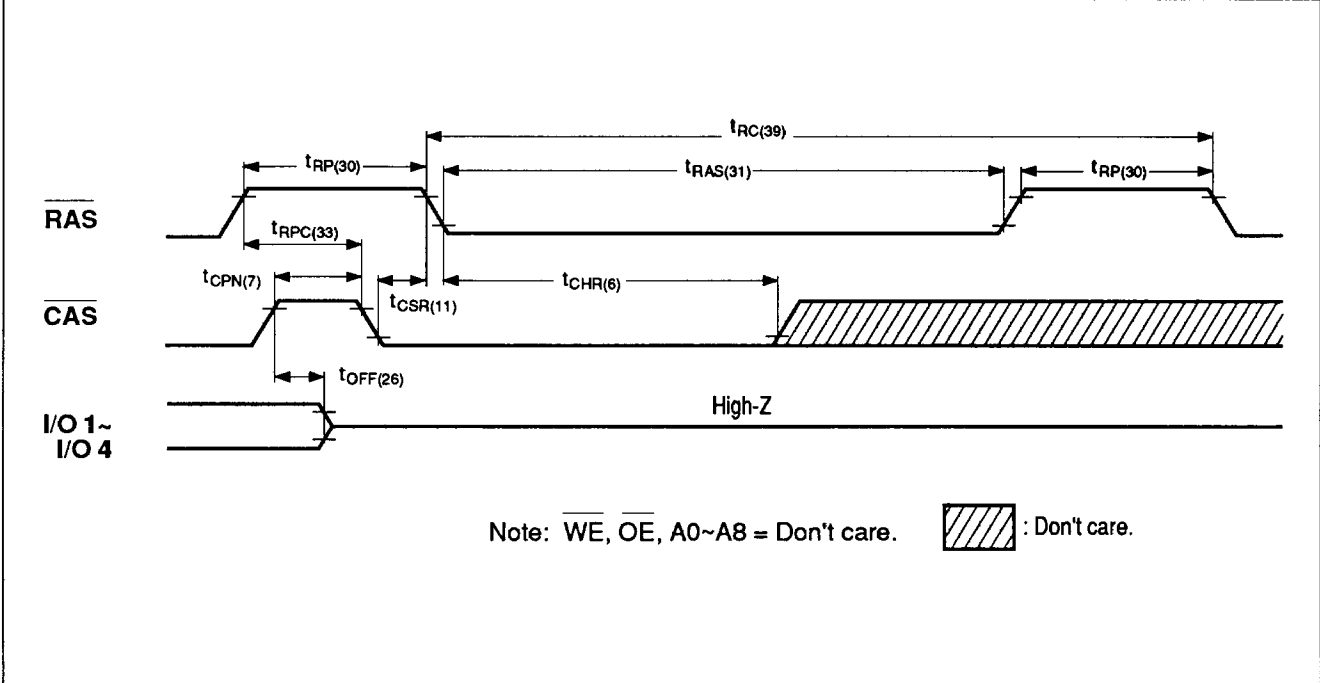
READ-MODIFY-WRITE CYCLE



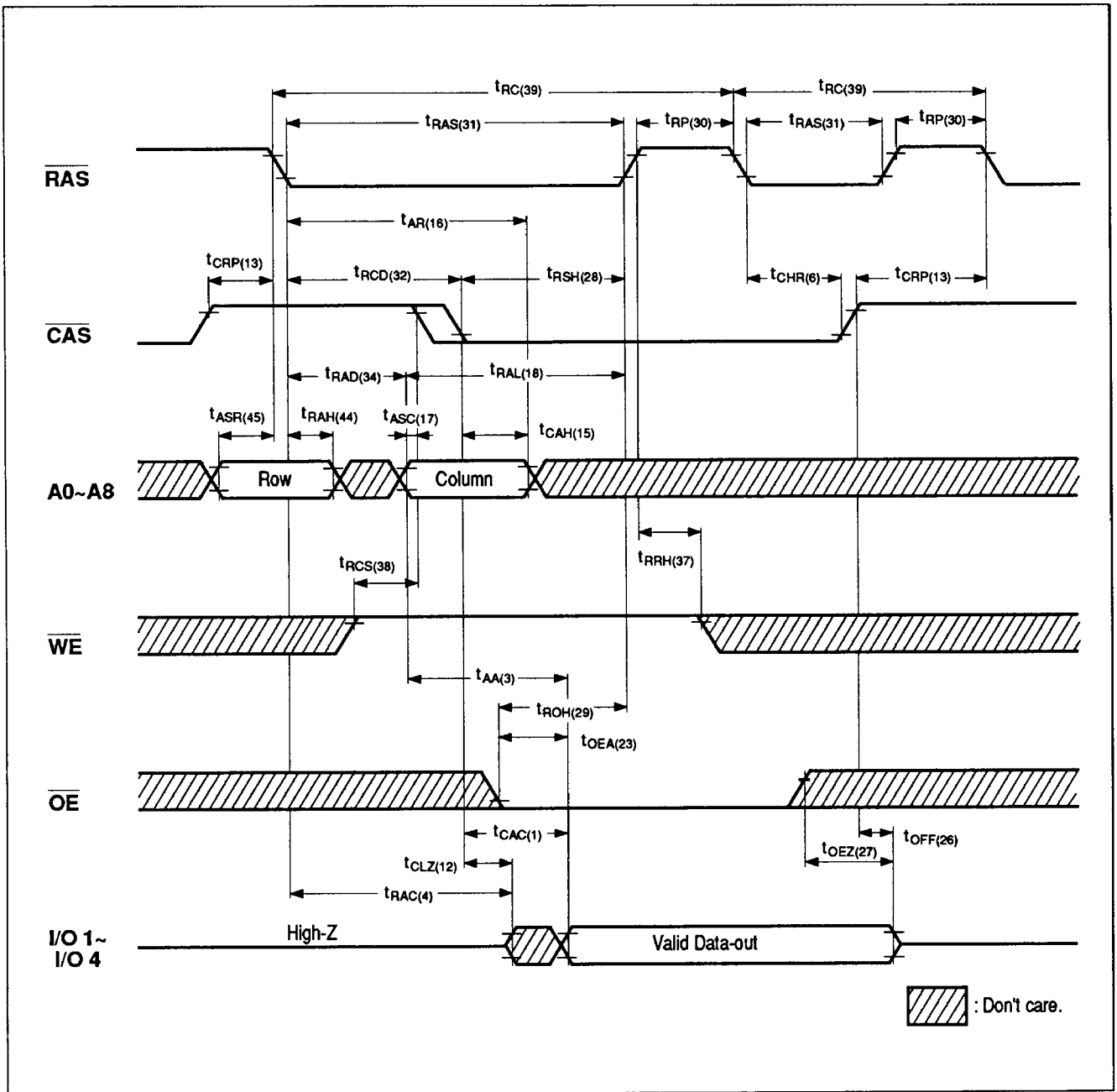
RAS ONLY REFRESH CYCLE



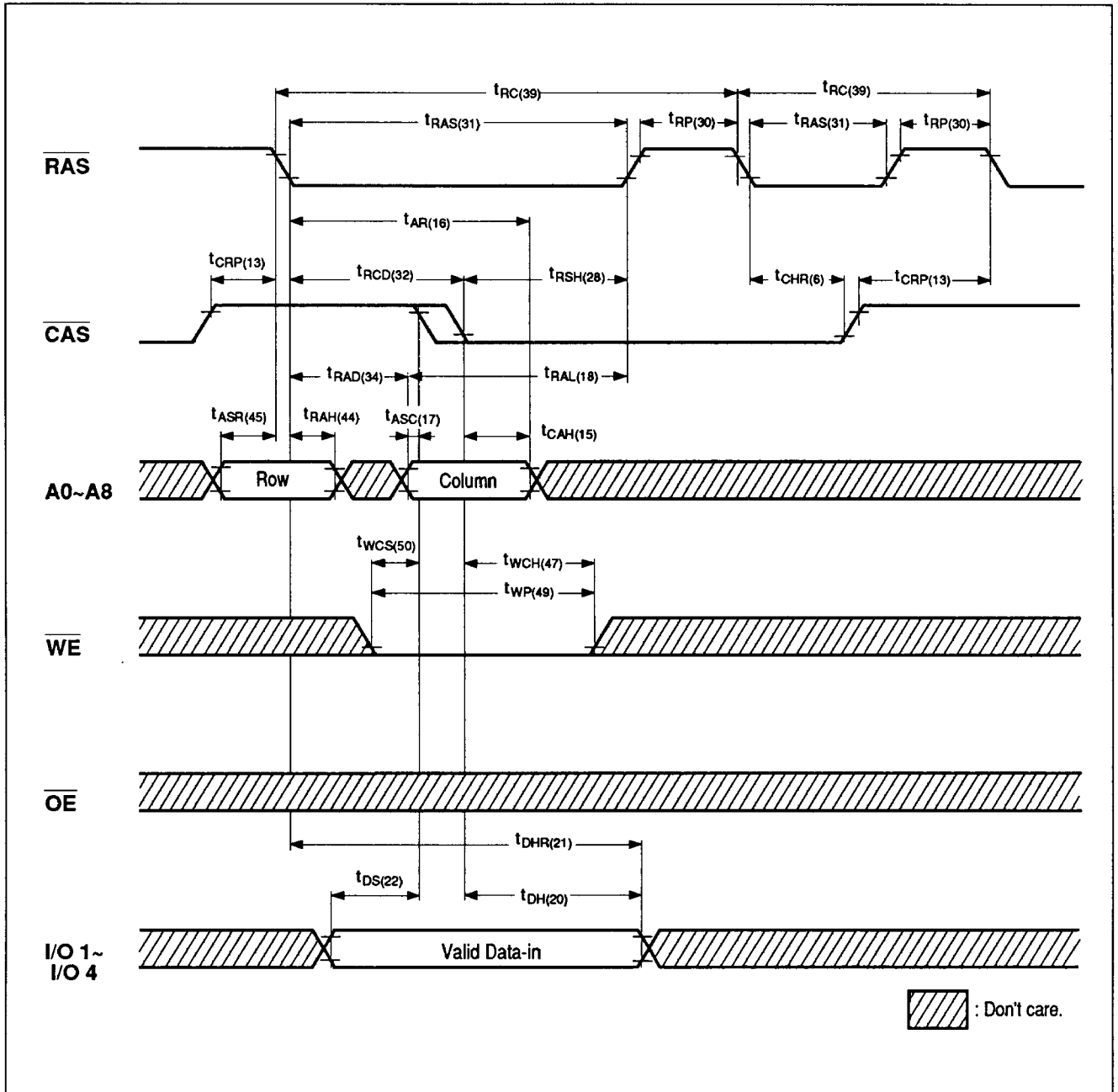
CAS BEFORE RAS REFRESH CYCLE



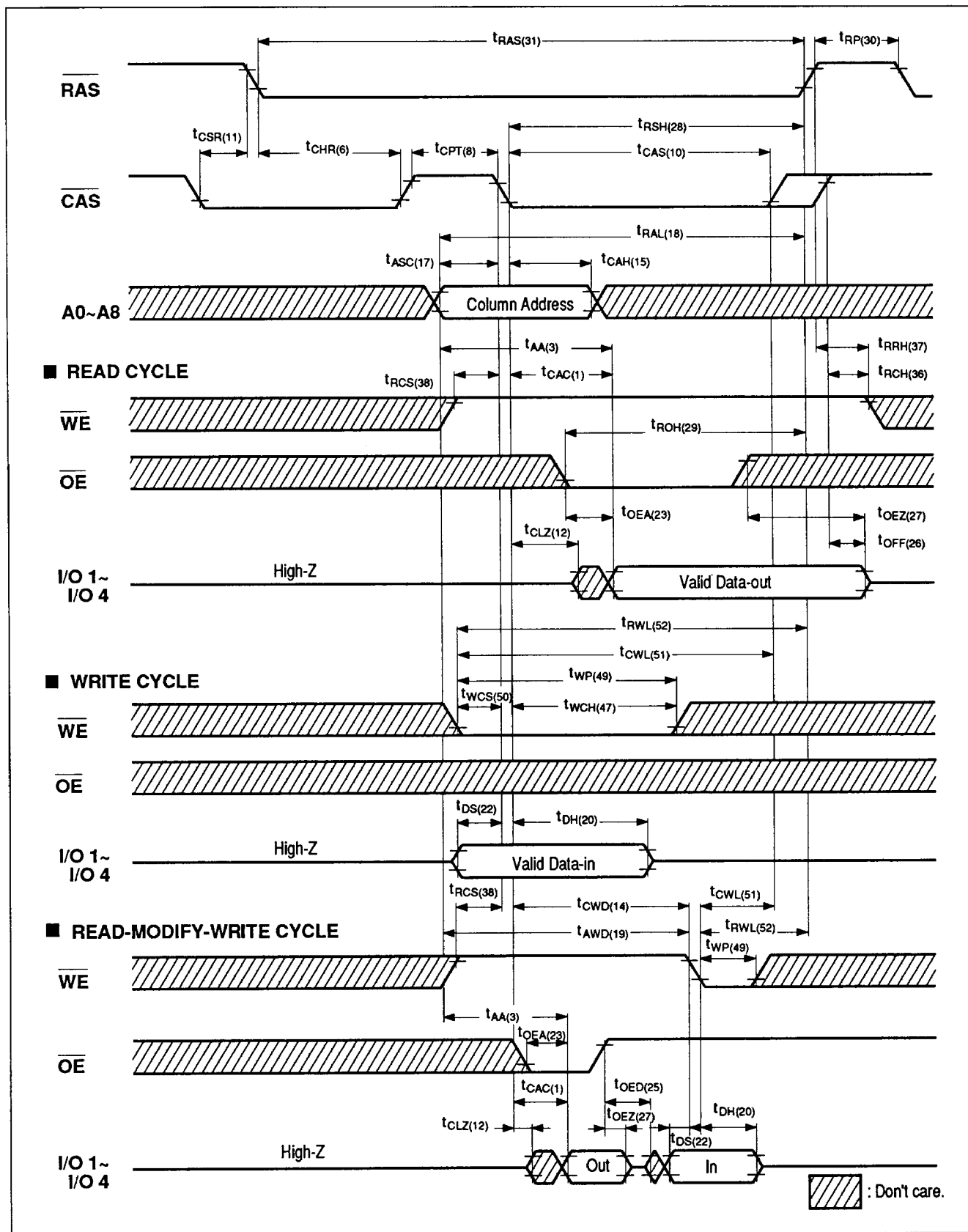
HIDDEN REFRESH CYCLE (READ)



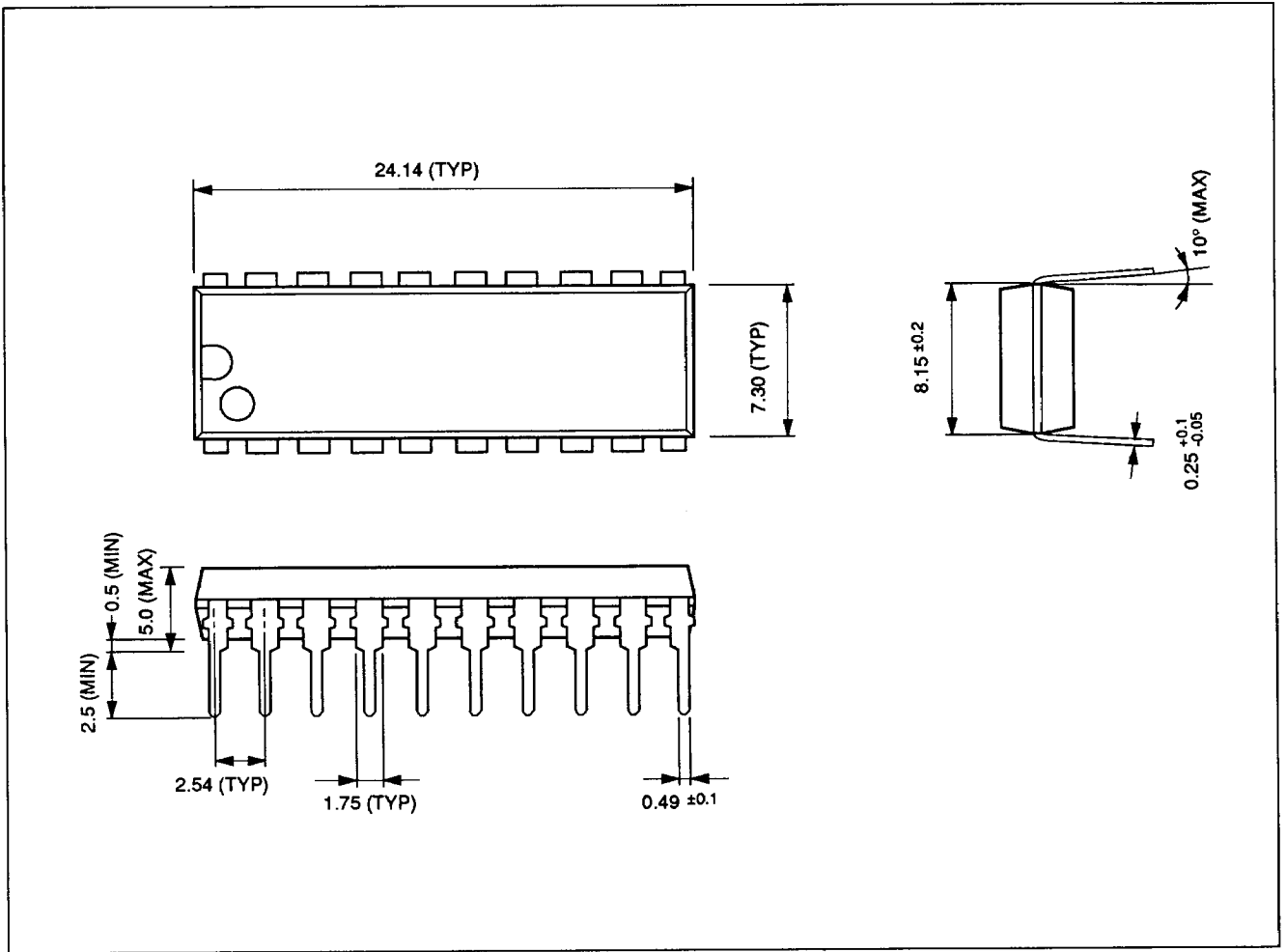
HIDDEN REFRESH CYCLE (EARLY WRITE)



CAS BEFORE RAS REFRESH COUNTER TEST CYCLE

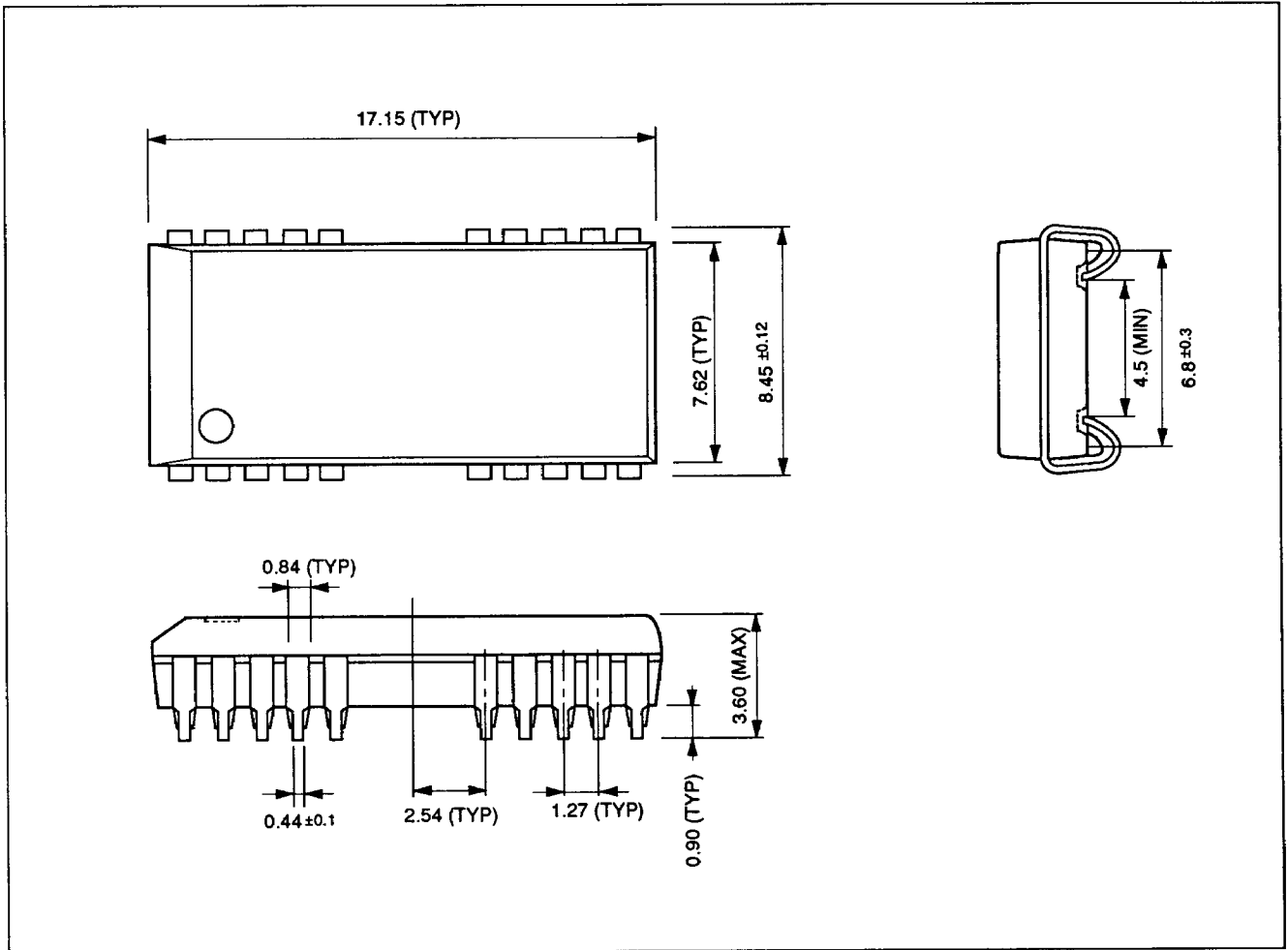


20 PIN PLASTIC DIP (300 mil) (Unit: mm)

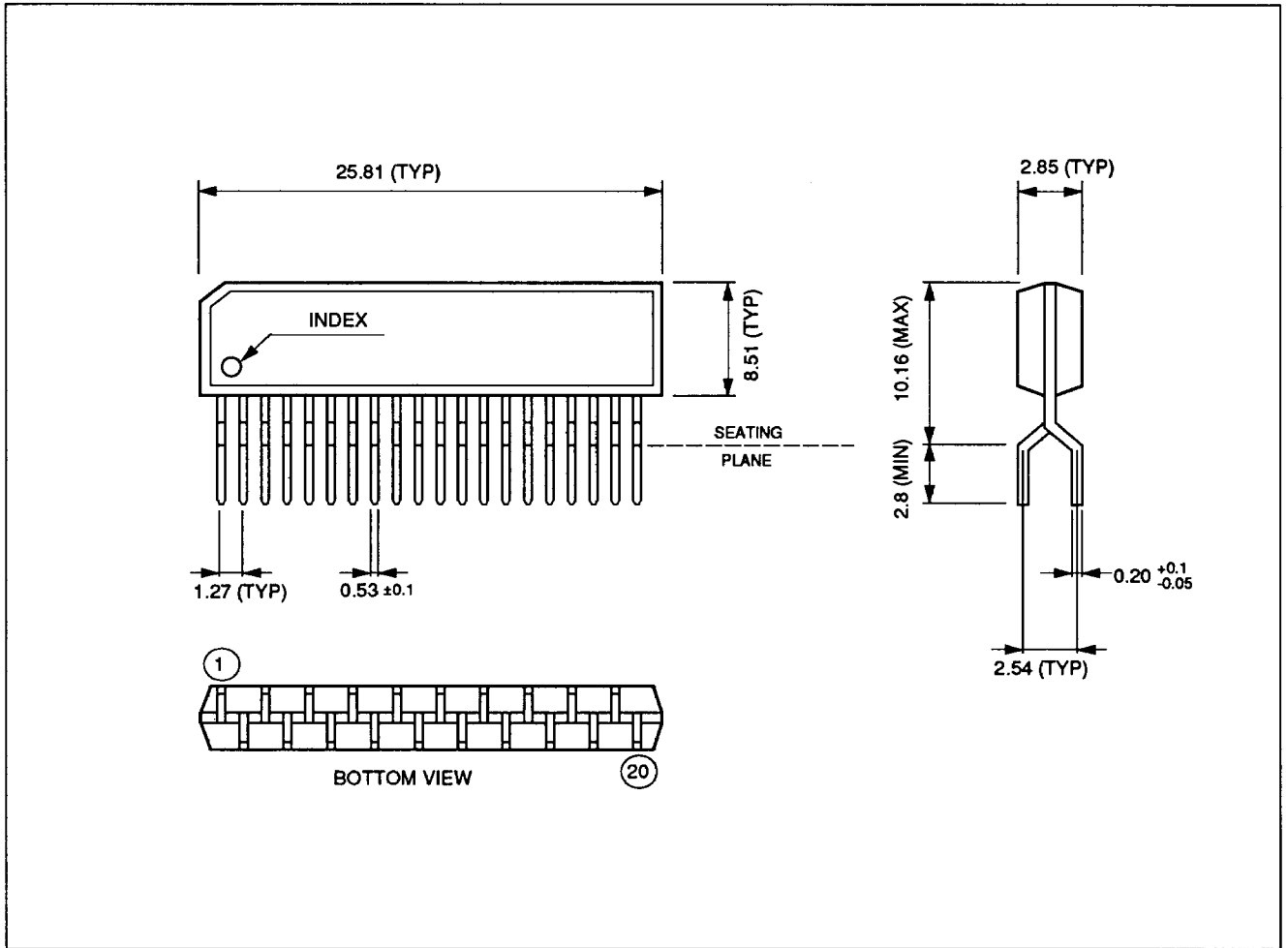


AAA1M204
CMOS 256K × 4 Dynamic RAM

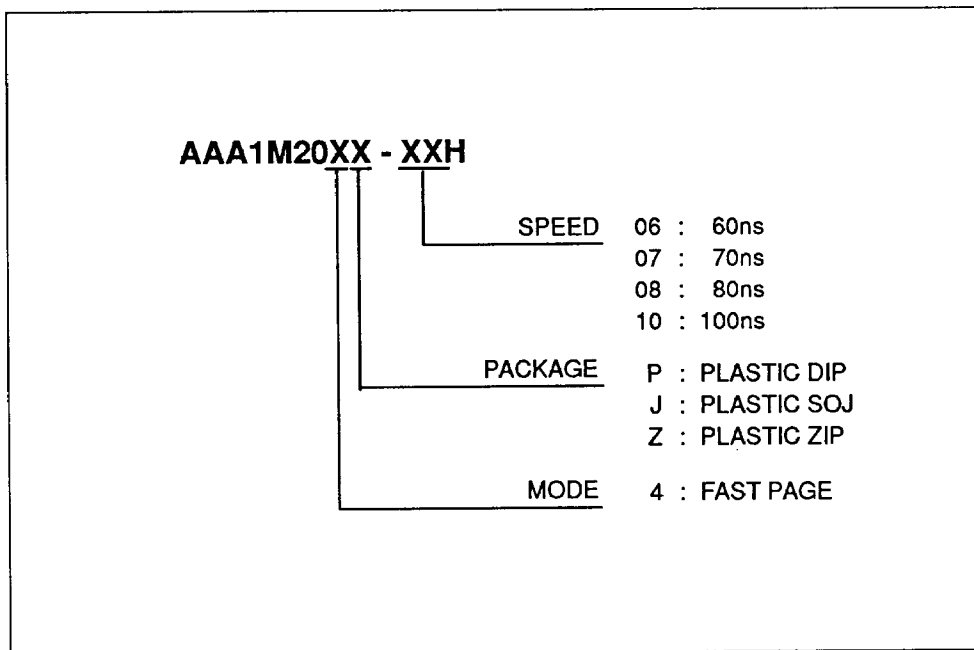
26 PIN PLASTIC SOJ (Unit: mm)



20 PIN PLASTIC ZIP (Unit: mm)



ORDERING INFORMATION



NMB SEMICONDUCTOR CO., LTD. reserves the right to make changes to the product described herein, and does not assume any liability which may occur due to the use or application of the product described.

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